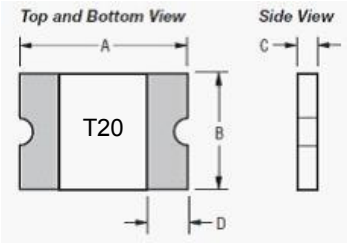
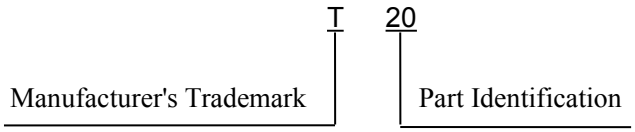
Product Introduction

1. Product Dimensions & Outline Drawing & marking（Unit:mm）





Model	A		B		C		D
	Min.	Max.	Min.	Max.	Min.	Max.	Min.
NSMD200	3.00	3.50	1.40	1.80	0.80	1.20	0.25

2. Electrical Properties

Model	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T (Max time to trip)		Pd_{typ} （W）	R_{min} (Ω)	$R1_{max}$ (Ω)
					(A)	(S)			
NSMD200	2.00	4.00	16	100	8.00	1.00	0.70	0.020	0.120

I_H: Holding Current: maximum current at which the device will not trip in 25℃ still air.

I_T: Tripping Current minimum current at which the device will trip in 25℃ still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25℃.

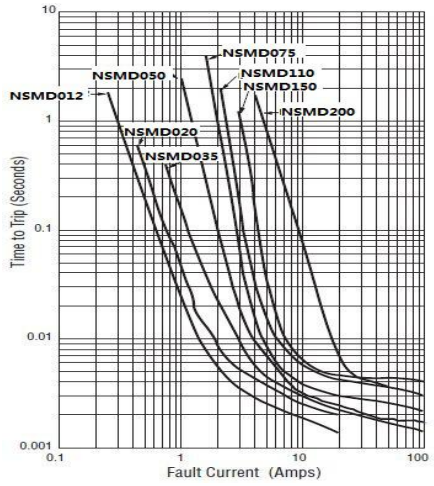
R_{max}: Maximum resistance of device prior to trip at 25℃.

$R1_{max}$: Maximum resistance of device is measured one hours post reflow at 25℃.

3. Thermal Derating Chart – I_{hold} (Amps)

Model	Ambient Operating Temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
NSMD200	2.88	2.61	2.28	2.00	1.80	1.66	1.51	1.39	1.19

4. Typical time to trip at 25℃



◆ Time to Trip curves represent typical performance of a device in a simulated application environment. Actual performance in specific customer applications may differ from these values due to the influence of other variables.